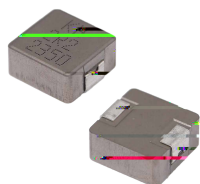


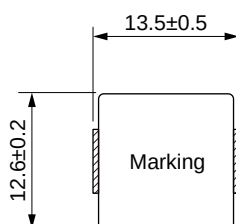
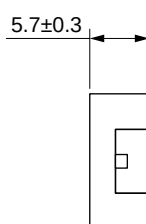
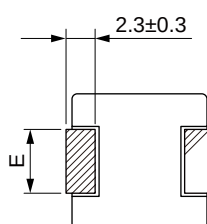
MDSA Series

SMD Low Profile High Current Molded Inductor

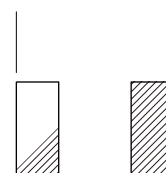
Size 1360



Dimensions: [mm]



Land Pattern: [mm]

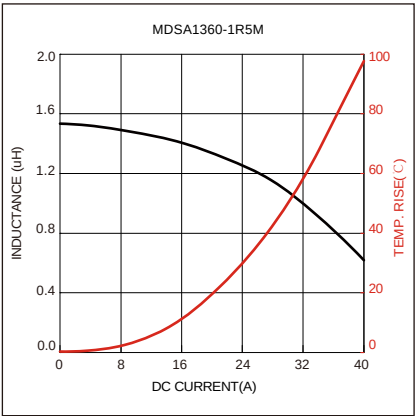
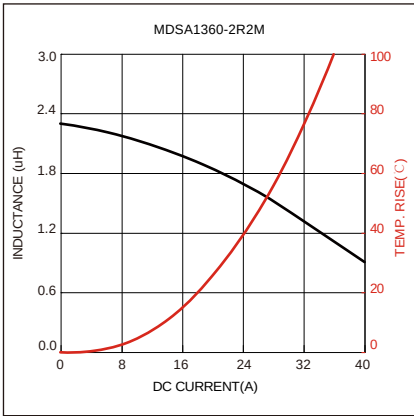
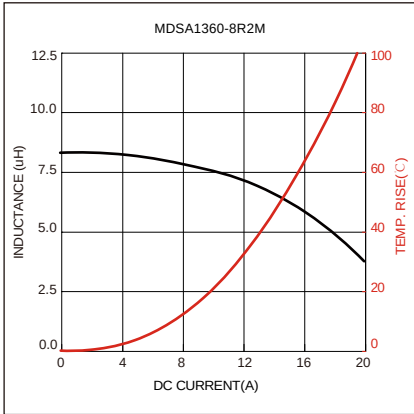
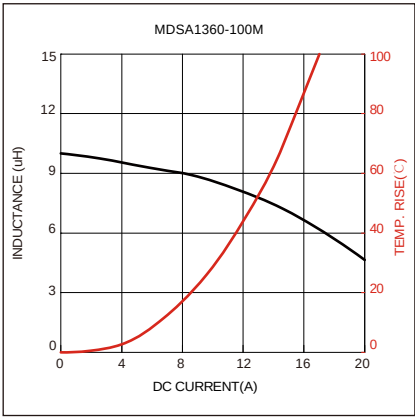
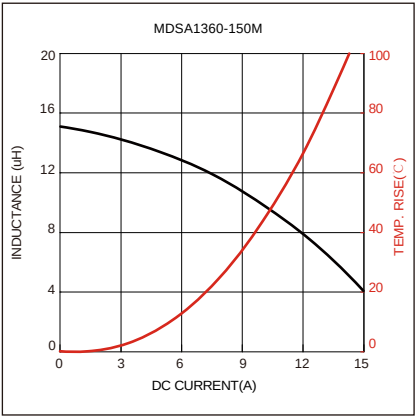
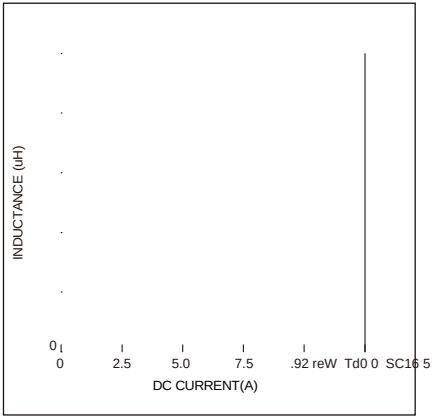


Electrical Properties:

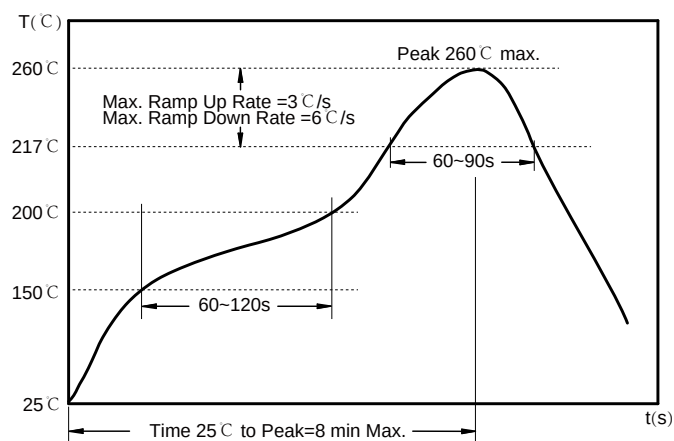
					L (μ H)	Steady St. Current Max. (A)	DC Resistance Typ. (m Ω)	DC Resistance Max. (m Ω)	Q (mm)
					30.0	28.0	2.42		4.0±0.3
				12.0	28.0	23.1		6.80	4.7±0.3
				11.0	17.0	14.9	13.7	16.2	4.7±0.3
			10.0	6.00	16.0	8.70	24.3	29.3	4.7±0.3
		5%			2.50			68.7	4.7±0.3

L to drop approximately 50%
The actual value of DC current when the temperature rise is $\Delta T \leq 40^\circ\text{C}$

Typical Electrical Characteristics:



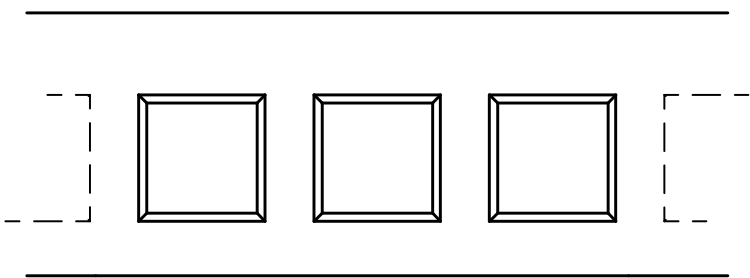
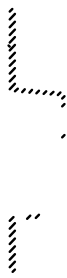
Soldering Reflow:



Preheat condition: $150 \sim 200^{\circ}\text{C} / 60 \sim 120 \text{ sec.}$
Allowed time above 217°C : 60~90 sec.
Max temperature: 260°C .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

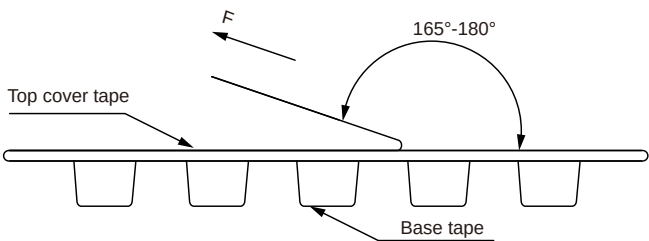
Packaging Information:

Tape Dimension :



A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
13.1 ± 0.1	14.0 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	16.0 ± 0.1	24.0 ± 0.3	6.3 ± 0.1	1.75 ± 0.1	0.50 ± 0.05

Peel force of top cover tape:

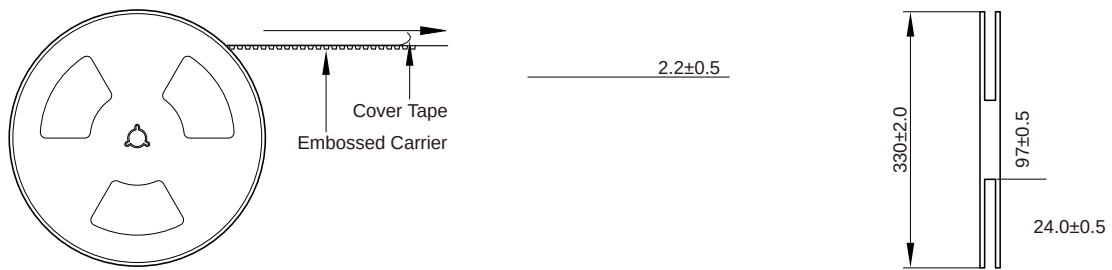


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing Inductance+period)
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Reel Dimension: [mm]



Packaging Quantity: